

Preliminary Amendment

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Title: PROCESS FOR PRODUCING AND APPARATUS FOR IMPROVING THE BONDING BETWEEN A PLASTIC AND A METAL

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

A semiconductor having a leadframe is disclosed. In one embodiment, a leadframe is disclosed to be fitted with a semiconductor chip ~~(2)~~ and is to be encapsulated with a plastic compound ~~(4)~~ has a metallic single-piece base body ~~(3)~~, to which an interlayer ~~(5)~~ is applied. The interlayer ~~(5)~~ has a surface ~~(6)~~ ~~comprising~~ including a matrix of islands ~~(14)~~ of remaining material of substantially uniform height, with voids ~~(10)~~ extending between said islands.

{Figure 1}